



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

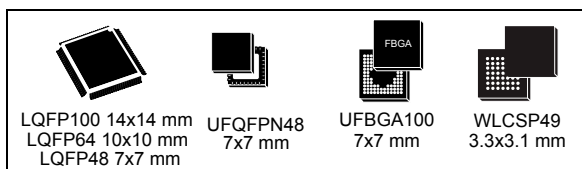


ARM[®]-based 32-bit MCU, 128 KB Flash, crystal-less USB FS 2.0,
12 timers, ADC, DAC and comm. interfaces, 1.8 V

Datasheet - production data

Features

- Core: ARM[®] 32-bit Cortex[®]-M0 CPU, frequency up to 48 MHz
- Memories
 - 128 Kbytes of Flash memory
 - 16 Kbytes of SRAM with HW parity
- CRC calculation unit
- Power management
 - Digital and I/O supply: $V_{DD} = 1.8\text{ V} \pm 8\%$
 - Analog supply: $V_{DDA} = V_{DD}$ to 3.6 V
 - Selected I/Os: $V_{DDIO2} = 1.65\text{ V}$ to 3.6 V
 - Low power modes: Sleep, Stop
 - V_{BAT} supply for RTC and backup registers
- Clock management
 - 4 to 32 MHz crystal oscillator
 - 32 kHz oscillator for RTC with calibration
 - Internal 8 MHz RC with x6 PLL option
 - Internal 40 kHz RC oscillator
 - Internal 48 MHz oscillator with automatic trimming based on ext. synchronization
- Up to 86 fast I/Os
 - All mappable on external interrupt vectors
 - Up to 67 I/Os with 5V tolerant capability and 19 with independent supply V_{DDIO2}
- Seven-channel DMA controller
- One 12-bit, 1.0 μs ADC (up to 16 channels)
 - Conversion range: 0 to 3.6 V
 - Separate analog supply: 2.4 V to 3.6 V
- Two independent 12-bit DAC channels
- Two fast low-power analog comparators with programmable input and output
- Up to 23 capacitive sensing channels for touchkey, linear and rotary touch sensors
- Calendar RTC with alarm and periodic wakeup from Stop



- 12 timers
 - One 16-bit advanced-control timer for six-channel PWM output
 - One 32-bit and seven 16-bit timers, with up to four IC/OC, OCN, usable for IR control decoding or DAC control
 - Independent and system watchdog timers
 - SysTick timer
- Communication interfaces
 - Two I²C interfaces supporting Fast Mode Plus (1 Mbit/s), one supporting SMBus/PMBus and wakeup
 - Four USARTs supporting master synchronous SPI and modem control, two with ISO7816 interface, LIN, IrDA, auto baud rate detection and wakeup feature
 - Two SPIs (18 Mbit/s) with 4 to 16 programmable bit frames, and with I²S interface multiplexed
 - USB 2.0 full-speed interface, able to run from internal 48 MHz oscillator and with BCD and LPM support
- HDMI CEC wakeup on header reception
- Serial wire debug (SWD)
- 96-bit unique ID
- All packages ECOPACK[®]2

Contents

- 1 Introduction 9**
- 2 Description 10**
- 3 Functional overview 13**
 - 3.1 ARM[®]-Cortex[®]-M0 core 13
 - 3.2 Memories 13
 - 3.3 Boot modes 13
 - 3.4 Cyclic redundancy check calculation unit (CRC) 14
 - 3.5 Power management 14
 - 3.5.1 Power supply schemes 14
 - 3.5.2 Power-on reset 14
 - 3.5.3 Low-power modes 14
 - 3.6 Clocks and startup 15
 - 3.7 General-purpose inputs/outputs (GPIOs) 16
 - 3.8 Direct memory access controller (DMA) 17
 - 3.9 Interrupts and events 17
 - 3.9.1 Nested vectored interrupt controller (NVIC) 17
 - 3.9.2 Extended interrupt/event controller (EXTI) 17
 - 3.10 Analog-to-digital converter (ADC) 17
 - 3.10.1 Temperature sensor 18
 - 3.10.2 Internal voltage reference (V_{REFINT}) 18
 - 3.10.3 V_{BAT} battery voltage monitoring 19
 - 3.11 Digital-to-analog converter (DAC) 19
 - 3.12 Comparators (COMP) 19
 - 3.13 Touch sensing controller (TSC) 19
 - 3.14 Timers and watchdogs 21
 - 3.14.1 Advanced-control timer (TIM1) 21
 - 3.14.2 General-purpose timers (TIM2, 3, 14, 15, 16, 17) 22
 - 3.14.3 Basic timers TIM6 and TIM7 23
 - 3.14.4 Independent watchdog (IWDG) 23
 - 3.14.5 System window watchdog (WWDG) 23
 - 3.14.6 SysTick timer 23

3.15	Real-time clock (RTC) and backup registers	23
3.16	Inter-integrated circuit interface (I ² C)	24
3.17	Universal synchronous/asynchronous receiver/transmitter (USART)	25
3.18	Serial peripheral interface (SPI) / Inter-integrated sound interface (I ² S)	26
3.19	High-definition multimedia interface (HDMI) - consumer electronics control (CEC)	26
3.20	Universal serial bus (USB)	27
3.21	Clock recovery system (CRS)	27
3.22	Serial wire debug port (SW-DP)	27
4	Pinouts and pin descriptions	28
5	Memory mapping	43
6	Electrical characteristics	46
6.1	Parameter conditions	46
6.1.1	Minimum and maximum values	46
6.1.2	Typical values	46
6.1.3	Typical curves	46
6.1.4	Loading capacitor	46
6.1.5	Pin input voltage	46
6.1.6	Power supply scheme	47
6.1.7	Current consumption measurement	48
6.2	Absolute maximum ratings	49
6.3	Operating conditions	51
6.3.1	General operating conditions	51
6.3.2	Operating conditions at power-up / power-down	51
6.3.3	Embedded reference voltage	52
6.3.4	Supply current characteristics	52
6.3.5	Wakeup time from low-power mode	61
6.3.6	External clock source characteristics	61
6.3.7	Internal clock source characteristics	65
6.3.8	PLL characteristics	69
6.3.9	Memory characteristics	69
6.3.10	EMC characteristics	70
6.3.11	Electrical sensitivity characteristics	71

6.3.12	I/O current injection characteristics	72
6.3.13	I/O port characteristics	73
6.3.14	NRST and NPOR pin characteristics	78
6.3.15	12-bit ADC characteristics	80
6.3.16	DAC electrical specifications	84
6.3.17	Comparator characteristics	86
6.3.18	Temperature sensor characteristics	88
6.3.19	V _{BAT} monitoring characteristics	88
6.3.20	Timer characteristics	88
6.3.21	Communication interfaces	89
7	Package information	96
7.1	UFBGA100 package information	96
7.2	LQFP100 package information	99
7.3	LQFP64 package information	102
7.4	WLCSP49 package information	105
7.5	LQFP48 package information	108
7.6	UFQFPN48 package information	111
7.7	Thermal characteristics	114
7.7.1	Reference document	114
7.7.2	Selecting the product temperature range	114
8	Ordering information	117
9	Revision history	118

List of tables

Table 1.	STM32F078CB/RB/VB family device features and peripheral counts	11
Table 2.	Temperature sensor calibration values	18
Table 3.	Internal voltage reference calibration values	18
Table 4.	Capacitive sensing GPIOs available on STM32F078CB/RB/VB devices	20
Table 5.	Number of capacitive sensing channels available on STM32F078CB/RB/VB devices	20
Table 6.	Timer feature comparison	21
Table 7.	Comparison of I ² C analog and digital filters	24
Table 8.	STM32F078CB/RB/VB I ² C implementation	25
Table 9.	STM32F078CB/RB/VB USART implementation	25
Table 10.	STM32F078CB/RB/VB SPI/I ² S implementation	26
Table 11.	Legend/abbreviations used in the pinout table	32
Table 12.	STM32F078CB/RB/VB pin definitions	32
Table 13.	Alternate functions selected through GPIOA_AFR registers for port A	39
Table 14.	Alternate functions selected through GPIOB_AFR registers for port B	40
Table 15.	Alternate functions selected through GPIOC_AFR registers for port C	41
Table 16.	Alternate functions selected through GPIOD_AFR registers for port D	41
Table 17.	Alternate functions selected through GPIOE_AFR registers for port E	42
Table 18.	Alternate functions available on port F	42
Table 19.	STM32F078CB/RB/VB peripheral register boundary addresses	44
Table 20.	Voltage characteristics	49
Table 21.	Current characteristics	50
Table 22.	Thermal characteristics	50
Table 23.	General operating conditions	51
Table 24.	Operating conditions at power-up / power-down	52
Table 25.	Embedded internal reference voltage	52
Table 26.	Typical and maximum current consumption from V _{DD} supply at V _{DD} = 1.8 V	53
Table 27.	Typical and maximum current consumption from the V _{DDA} supply	55
Table 28.	Typical and maximum current consumption from the V _{BAT} supply	55
Table 29.	Typical current consumption, code executing from Flash memory, running from HSE 8 MHz crystal	56
Table 30.	Typical and maximum consumption in Stop mode	57
Table 31.	Switching output I/O current consumption	58
Table 32.	Peripheral current consumption	59
Table 33.	Low-power mode wakeup timings	61
Table 34.	High-speed external user clock characteristics	61
Table 35.	Low-speed external user clock characteristics	62
Table 36.	HSE oscillator characteristics	63
Table 37.	LSE oscillator characteristics (f _{LSE} = 32.768 kHz)	64
Table 38.	HSI oscillator characteristics	66
Table 39.	HSI14 oscillator characteristics	67
Table 40.	HSI48 oscillator characteristics	68
Table 41.	LSI oscillator characteristics	69
Table 42.	PLL characteristics	69
Table 43.	Flash memory characteristics	69
Table 44.	Flash memory endurance and data retention	70
Table 45.	EMS characteristics	70
Table 46.	EMI characteristics	71

Table 47.	ESD absolute maximum ratings	72
Table 48.	Electrical sensitivities	72
Table 49.	I/O current injection susceptibility	73
Table 50.	I/O static characteristics	73
Table 51.	Output voltage characteristics	76
Table 52.	I/O AC characteristics	77
Table 53.	NRST pin characteristics	79
Table 54.	NPOR pin characteristics	80
Table 55.	ADC characteristics	80
Table 56.	R_{AIN} max for $f_{ADC} = 14$ MHz	81
Table 57.	ADC accuracy	82
Table 58.	DAC characteristics	84
Table 59.	Comparator characteristics	86
Table 60.	TS characteristics	88
Table 61.	V_{BAT} monitoring characteristics	88
Table 62.	TIMx characteristics	88
Table 63.	IWDG min/max timeout period at 40 kHz (LSI)	89
Table 64.	WWDG min/max timeout value at 48 MHz (PCLK)	89
Table 65.	I ² C analog filter characteristics	90
Table 66.	SPI characteristics	90
Table 67.	I ² S characteristics	92
Table 68.	USB electrical characteristics	95
Table 69.	UFBGA100 package mechanical data	96
Table 70.	UFBGA100 recommended PCB design rules	97
Table 71.	LQPF100 package mechanical data	99
Table 72.	LQFP64 package mechanical data	102
Table 73.	WLCSP49 package mechanical data	106
Table 74.	LQFP48 package mechanical data	109
Table 75.	UFQFPN48 package mechanical data	112
Table 76.	Package thermal characteristics	114
Table 77.	Ordering information scheme	117
Table 78.	Document revision history	118

List of figures

Figure 1.	Block diagram	12
Figure 2.	Clock tree	16
Figure 3.	UFBGA100 package pinout	28
Figure 4.	LQFP100 package pinout	29
Figure 5.	LQFP64 package pinout	30
Figure 6.	LQFP48 package pinout	30
Figure 7.	UFQFPN48 package pinout	31
Figure 8.	WLCSP49 package pinout	31
Figure 9.	STM32F078CB/RB/VB memory map	43
Figure 10.	Pin loading conditions	46
Figure 11.	Pin input voltage	46
Figure 12.	Power supply scheme	47
Figure 13.	Current consumption measurement scheme	48
Figure 14.	High-speed external clock source AC timing diagram	62
Figure 15.	Low-speed external clock source AC timing diagram	62
Figure 16.	Typical application with an 8 MHz crystal	64
Figure 17.	Typical application with a 32.768 kHz crystal	65
Figure 18.	HSI oscillator accuracy characterization results for soldered parts	66
Figure 19.	HSI14 oscillator accuracy characterization results	67
Figure 20.	HSI48 oscillator accuracy characterization results	68
Figure 21.	TC and TTA I/O input characteristics	75
Figure 22.	Five volt tolerant (FT and FTf) I/O input characteristics	75
Figure 23.	I/O AC characteristics definition	78
Figure 24.	Recommended NRST pin protection	79
Figure 25.	ADC accuracy characteristics	83
Figure 26.	Typical connection diagram using the ADC	83
Figure 27.	12-bit buffered / non-buffered DAC	85
Figure 28.	Maximum V_{REFINT} scaler startup time from power down	87
Figure 29.	SPI timing diagram - slave mode and CPHA = 0	91
Figure 30.	SPI timing diagram - slave mode and CPHA = 1	91
Figure 31.	SPI timing diagram - master mode	92
Figure 32.	I ² S slave timing diagram (Philips protocol)	93
Figure 33.	I ² S master timing diagram (Philips protocol)	94
Figure 34.	UFBGA100 package outline	96
Figure 35.	Recommended footprint for UFBGA100 package	97
Figure 36.	UFBGA100 package marking example	98
Figure 37.	LQFP100 package outline	99
Figure 38.	Recommended footprint for LQFP100 package	100
Figure 39.	LQFP100 package marking example	101
Figure 40.	LQFP64 package outline	102
Figure 41.	Recommended footprint for LQFP64 package	103
Figure 42.	LQFP64 package marking example	104
Figure 43.	WLCSP49 package outline	105
Figure 44.	WLCSP49 package marking example	107
Figure 45.	LQFP48 package outline	108
Figure 46.	Recommended footprint for LQFP48 package	109
Figure 47.	LQFP48 package marking example	110
Figure 48.	UFQFPN48 package outline	111

Figure 49. Recommended footprint for UFQFPN48 package	112
Figure 50. UFQFPN48 package marking example	113
Figure 51. LQFP64 P_D max versus T_A	116

1 Introduction

This datasheet provides the ordering information and mechanical device characteristics of the STM32F078CB/RB/VB microcontrollers.

This document should be read in conjunction with the STM32F0xxxx reference manual (RM0091). The reference manual is available from the STMicroelectronics website www.st.com.

For information on the ARM® Cortex®-M0 core, please refer to the Cortex®-M0 Technical Reference Manual, available from the www.arm.com website.



2 Description

The STM32F078CB/RB/VB microcontrollers incorporate the high-performance ARM[®] Cortex[®]-M0 32-bit RISC core operating at up to 48 MHz frequency, high-speed embedded memories (128 Kbytes of Flash memory and 16 Kbytes of SRAM), and an extensive range of enhanced peripherals and I/Os. All devices offer standard communication interfaces (two I²Cs, two SPI/I²S, one HDMI CEC and four USARTs), one USB Full-speed device (crystal-less), one 12-bit ADC, one 12-bit DAC with two channels, seven 16-bit timers, one 32-bit timer and an advanced-control PWM timer.

The STM32F078CB/RB/VB microcontrollers operate in the -40 to +85 °C and -40 to +105 °C temperature ranges from a 1.8 V ± 8% power supply. A comprehensive set of power-saving modes allows the design of low-power applications.

The STM32F078CB/RB/VB microcontrollers include devices in six different packages ranging from 48 pins to 100 pins with a die form also available upon request. Depending on the device chosen, different sets of peripherals are included.

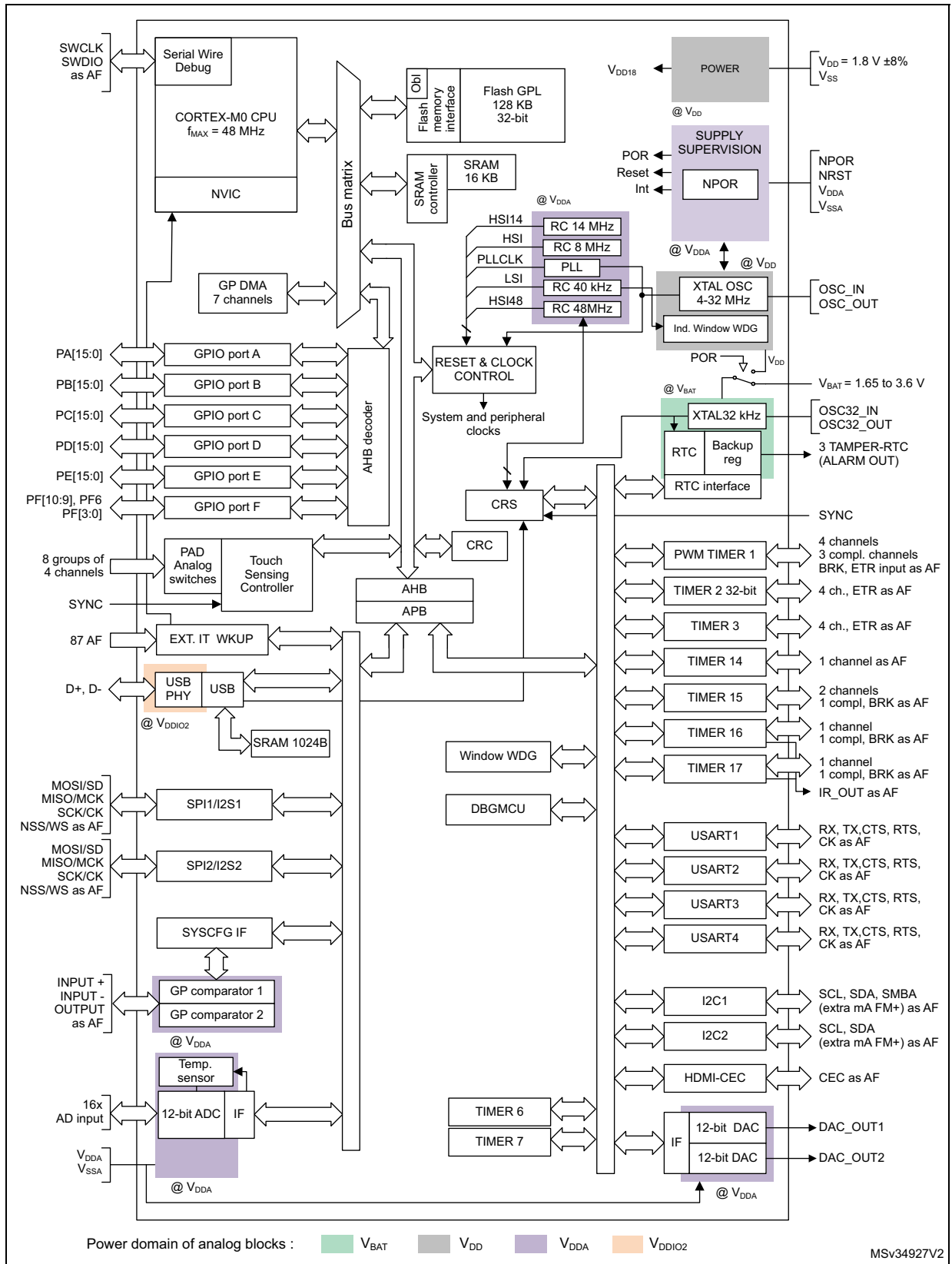
These features make the STM32F078CB/RB/VB microcontrollers suitable for a wide range of applications such as application control and user interfaces, hand-held equipment, A/V receivers and digital TV, PC peripherals, gaming and GPS platforms, industrial applications, PLCs, inverters, printers, scanners, alarm systems, video intercoms and HVACs.

Table 1. STM32F078CB/RB/VB family device features and peripheral counts

Peripheral		STM32F078CB	STM32F078RB	STM32F078VB
Flash memory (Kbyte)		128		
SRAM (Kbyte)		16		
Timers	Advanced control	1 (16-bit)		
	General purpose	5 (16-bit) 1 (32-bit)		
	Basic	2 (16-bit)		
Comm. interfaces	SPI [I ² S] ⁽¹⁾	2 [2]		
	I ² C	2		
	USART	4		
	USB	1		
	CEC	1		
12-bit ADC (number of channels)		1 (10 ext. + 3 int.)	1 (16 ext. + 3 int.)	
12-bit DAC (number of channels)		1 (2)		
Analog comparator		2		
GPIOs		36	50	86
Capacitive sensing channels		16	17	23
Max. CPU frequency		48 MHz		
Operating voltage		V _{DD} = 1.8 V ± 8%, V _{DDA} = from V _{DD} to 3.6 V		
Operating temperature		Ambient operating temperature: -40°C to 85°C / -40°C to 105°C Junction temperature: -40°C to 105°C / -40°C to 125°C		
Packages		LQFP48 UFQFPN48 WLCSP49	LQFP64	LQFP100 UFBGA100

1. The SPI interface can be used either in SPI mode or in I²S audio mode.

Figure 1. Block diagram



3 Functional overview

Figure 1 shows the general block diagram of the STM32F078CB/RB/VB devices.

3.1 ARM[®]-Cortex[®]-M0 core

The ARM[®] Cortex[®]-M0 is a generation of ARM 32-bit RISC processors for embedded systems. It has been developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced system response to interrupts.

The ARM[®] Cortex[®]-M0 processors feature exceptional code-efficiency, delivering the high performance expected from an ARM core, with memory sizes usually associated with 8- and 16-bit devices.

The STM32F078CB/RB/VB devices embed ARM core and are compatible with all ARM tools and software.

3.2 Memories

The device has the following features:

- 16 Kbytes of embedded SRAM accessed (read/write) at CPU clock speed with 0 wait states and featuring embedded parity checking with exception generation for fail-critical applications.
- The non-volatile memory is divided into two arrays:
 - 128 Kbytes of embedded Flash memory for programs and data
 - Option bytes

The option bytes are used to write-protect the memory (with 4 KB granularity) and/or readout-protect the whole memory with the following options:

- Level 0: no readout protection
- Level 1: memory readout protection, the Flash memory cannot be read from or written to if either debug features are connected or boot in RAM is selected
- Level 2: chip readout protection, debug features (Cortex[®]-M0 serial wire) and boot in RAM selection disabled

3.3 Boot modes

At startup, the boot pin and boot selector option bit are used to select one of the three boot options:

- boot from User Flash memory
- boot from System Memory
- boot from embedded SRAM

The boot loader is located in System Memory. It is used to reprogram the Flash memory by using USART on pins PA14/PA15 or PA9/PA10 or I²C on pins PB6/PB7 or through the USB DFU interface.

3.4 Cyclic redundancy check calculation unit (CRC)

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code using a configurable generator polynomial value and size.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps compute a signature of the software during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

3.5 Power management

3.5.1 Power supply schemes

- $V_{DD} = V_{DDIO1} = 1.8\text{ V} \pm 8\%$: external power supply for I/Os (V_{DDIO1}) and digital logic. It is provided externally through VDD pins.
- V_{DDA} = from V_{DD} to 3.6 V: external analog power supply for ADC, DAC, RCs and PLL (minimum voltage to be applied to V_{DDA} is 2.4 V when the ADC or DAC are used). It is provided externally through VDDA pin. The V_{DDA} voltage level must be always greater or equal to the V_{DD} voltage level and must be established first.
- $V_{DDIO2} = 1.65$ to 3.6 V: external power supply for marked I/Os. V_{DDIO2} is provided externally through the VDDIO2 pin. The V_{DDIO2} voltage level is completely independent from V_{DD} or V_{DDA} , but it must not be provided without a valid supply on V_{DD} . The V_{DDIO2} supply is monitored and compared with the internal reference voltage (V_{REFINT}). When the V_{DDIO2} is below this threshold, all the I/Os supplied from this rail are disabled by hardware. The output of this comparator is connected to EXTI line 31 and it can be used to generate an interrupt. Refer to the pinout diagrams or tables for concerned I/Os list.
- $V_{BAT} = 1.65$ to 3.6 V: power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when V_{DD} is not present.

For more details on how to connect power pins, refer to [Figure 12: Power supply scheme](#).

3.5.2 Power-on reset

To guarantee a proper power-on reset, the NPOR pin must be held low until V_{DD} is stable. When V_{DD} is stable, the reset state can be exited either by:

- putting the NPOR pin in high impedance (NPOR pin has an internal pull-up), or by
- forcing the pin to high level by connecting it to V_{DDA}

3.5.3 Low-power modes

The STM32F078CB/RB/VB microcontrollers support two low-power modes to achieve the best compromise between low power consumption, short startup time and available wakeup sources:

- **Sleep mode**

In Sleep mode, only the CPU is stopped. All peripherals continue to operate and can wake up the CPU when an interrupt/event occurs.

- **Stop mode**

Stop mode achieves very low power consumption while retaining the content of SRAM and registers. All clocks in the 1.8 V domain are stopped, the PLL, the HSI RC and the HSE crystal oscillators are disabled.

The device can be woken up from Stop mode by any of the EXTI lines. The EXTI line source can be one of the 16 external lines, RTC, I2C1, USART1, USART2, USB, COMPx, V_{DDIO2} supply comparator or the CEC.

The CEC, USART1, USART2 and I2C1 peripherals can be configured to enable the HSI RC oscillator so as to get clock for processing incoming data.

Note: The RTC, the IWDG, and the corresponding clock sources are not stopped by entering Stop mode.

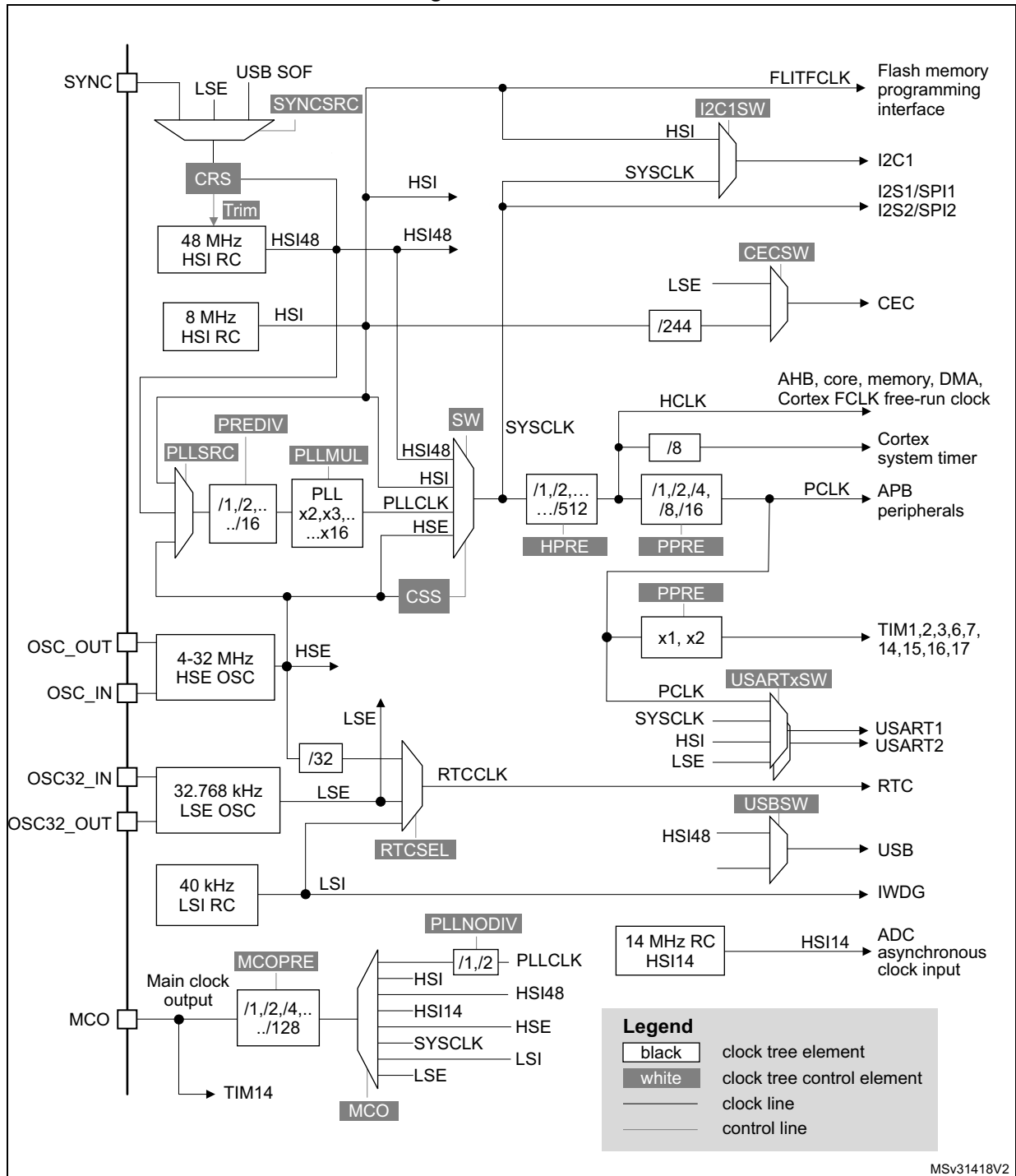
3.6 Clocks and startup

System clock selection is performed on startup, however the internal RC 8 MHz oscillator is selected as default CPU clock on reset. An external 4-32 MHz clock can be selected, in which case it is monitored for failure. If failure is detected, the system automatically switches back to the internal RC oscillator. A software interrupt is generated if enabled. Similarly, full interrupt management of the PLL clock entry is available when necessary (for example on failure of an indirectly used external crystal, resonator or oscillator).

Several prescalers allow the application to configure the frequency of the AHB and the APB domains. The maximum frequency of the AHB and the APB domains is 48 MHz.

Additionally, also the internal RC 48 MHz oscillator can be selected for system clock or PLL input source. This oscillator can be automatically fine-trimmed by the means of the CRS peripheral using the external synchronization.

Figure 2. Clock tree



3.7 General-purpose inputs/outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions.

The I/O configuration can be locked if needed following a specific sequence in order to avoid spurious writing to the I/Os registers.

3.8 Direct memory access controller (DMA)

The 7-channel general-purpose DMAs manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers.

The DMA supports circular buffer management, removing the need for user code intervention when the controller reaches the end of the buffer.

Each channel is connected to dedicated hardware DMA requests, with support for software trigger on each channel. Configuration is made by software and transfer sizes between source and destination are independent.

DMA can be used with the main peripherals: SPIx, I2Sx, I2Cx, USARTx, all TIMx timers (except TIM14), DAC and ADC.

3.9 Interrupts and events

3.9.1 Nested vectored interrupt controller (NVIC)

The STM32F0xx family embeds a nested vectored interrupt controller able to handle up to 32 maskable interrupt channels (not including the 16 interrupt lines of Cortex[®]-M0) and 4 priority levels.

- Closely coupled NVIC gives low latency interrupt processing
- Interrupt entry vector table address passed directly to the core
- Closely coupled NVIC core interface
- Allows early processing of interrupts
- Processing of late arriving higher priority interrupts
- Support for tail-chaining
- Processor state automatically saved
- Interrupt entry restored on interrupt exit with no instruction overhead

This hardware block provides flexible interrupt management features with minimal interrupt latency.

3.9.2 Extended interrupt/event controller (EXTI)

The extended interrupt/event controller consists of 32 edge detector lines used to generate interrupt/event requests and wake-up the system. Each line can be independently configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The EXTI can detect an external line with a pulse width shorter than the internal clock period. Up to 86 GPIOs can be connected to the 16 external interrupt lines.

3.10 Analog-to-digital converter (ADC)

The 12-bit analog-to-digital converter has up to 16 external and 3 internal (temperature

sensor, voltage reference, VBAT voltage measurement) channels and performs conversions in single-shot or scan modes. In scan mode, automatic conversion is performed on a selected group of analog inputs.

The ADC can be served by the DMA controller.

An analog watchdog feature allows very precise monitoring of the converted voltage of one, some or all selected channels. An interrupt is generated when the converted voltage is outside the programmed thresholds.

3.10.1 Temperature sensor

The temperature sensor (TS) generates a voltage V_{SENSE} that varies linearly with temperature.

The temperature sensor is internally connected to the ADC_IN16 input channel which is used to convert the sensor output voltage into a digital value.

The sensor provides good linearity but it has to be calibrated to obtain good overall accuracy of the temperature measurement. As the offset of the temperature sensor varies from chip to chip due to process variation, the uncalibrated internal temperature sensor is suitable for applications that detect temperature changes only.

To improve the accuracy of the temperature sensor measurement, each device is individually factory-calibrated by ST. The temperature sensor factory calibration data are stored by ST in the system memory area, accessible in read-only mode.

Table 2. Temperature sensor calibration values

Calibration value name	Description	Memory address
TS_CAL1	TS ADC raw data acquired at a temperature of 30 °C (± 5 °C), $V_{DDA} = 3.3$ V (± 10 mV)	0x1FFF F7B8 - 0x1FFF F7B9
TS_CAL2	TS ADC raw data acquired at a temperature of 110 °C (± 5 °C), $V_{DDA} = 3.3$ V (± 10 mV)	0x1FFF F7C2 - 0x1FFF F7C3

3.10.2 Internal voltage reference (V_{REFINT})

The internal voltage reference (V_{REFINT}) provides a stable (bandgap) voltage output for the ADC and comparators. V_{REFINT} is internally connected to the ADC_IN17 input channel. The precise voltage of V_{REFINT} is individually measured for each part by ST during production test and stored in the system memory area. It is accessible in read-only mode.

Table 3. Internal voltage reference calibration values

Calibration value name	Description	Memory address
VREFINT_CAL	Raw data acquired at a temperature of 30 °C (± 5 °C), $V_{DDA} = 3.3$ V (± 10 mV)	0x1FFF F7BA - 0x1FFF F7BB

3.10.3 V_{BAT} battery voltage monitoring

This embedded hardware feature allows the application to measure the V_{BAT} battery voltage using the internal ADC channel ADC_IN18. As the V_{BAT} voltage may be higher than V_{DDA} , and thus outside the ADC input range, the V_{BAT} pin is internally connected to a bridge divider by 2. As a consequence, the converted digital value is half the V_{BAT} voltage.

3.11 Digital-to-analog converter (DAC)

The two 12-bit buffered DAC channels can be used to convert digital signals into analog voltage signal outputs. The chosen design structure is composed of integrated resistor strings and an amplifier in non-inverting configuration.

This digital Interface supports the following features:

- 8-bit or 12-bit monotonic output
- Left or right data alignment in 12-bit mode
- Synchronized update capability
- Noise-wave generation
- Triangular-wave generation
- Dual DAC channel independent or simultaneous conversions
- DMA capability for each channel
- External triggers for conversion

Six DAC trigger inputs are used in the device. The DAC is triggered through the timer trigger outputs and the DAC interface is generating its own DMA requests.

3.12 Comparators (COMP)

The device embeds two fast rail-to-rail low-power comparators with programmable reference voltage (internal or external), hysteresis and speed (low speed for low power) and with selectable output polarity.

The reference voltage can be one of the following:

- External I/O
- DAC output pins
- Internal reference voltage or submultiple (1/4, 1/2, 3/4). Refer to [Table 25: Embedded internal reference voltage](#) for the value and precision of the internal reference voltage.

Both comparators can wake up from STOP mode, generate interrupts and breaks for the timers and can be also combined into a window comparator.

3.13 Touch sensing controller (TSC)

The STM32F078CB/RB/VB devices provide a simple solution for adding capacitive sensing functionality to any application. These devices offer up to 23 capacitive sensing channels distributed over 8 analog I/O groups.

Capacitive sensing technology is able to detect the presence of a finger near a sensor which is protected from direct touch by a dielectric (glass, plastic...). The capacitive variation

introduced by the finger (or any conductive object) is measured using a proven implementation based on a surface charge transfer acquisition principle. It consists in charging the sensor capacitance and then transferring a part of the accumulated charges into a sampling capacitor until the voltage across this capacitor has reached a specific threshold. To limit the CPU bandwidth usage, this acquisition is directly managed by the hardware touch sensing controller and only requires few external components to operate. For operation, one capacitive sensing GPIO in each group is connected to an external capacitor and cannot be used as effective touch sensing channel.

The touch sensing controller is fully supported by the STMTouch touch sensing firmware library, which is free to use and allows touch sensing functionality to be implemented reliably in the end application.

Table 4. Capacitive sensing GPIOs available on STM32F078CB/RB/VB devices

Group	Capacitive sensing signal name	Pin name	Group	Capacitive sensing signal name	Pin name
1	TSC_G1_IO1	PA0	5	TSC_G5_IO1	PB3
	TSC_G1_IO2	PA1		TSC_G5_IO2	PB4
	TSC_G1_IO3	PA2		TSC_G5_IO3	PB6
	TSC_G1_IO4	PA3		TSC_G5_IO4	PB7
2	TSC_G2_IO1	PA4	6	TSC_G6_IO1	PB11
	TSC_G2_IO2	PA5		TSC_G6_IO2	PB12
	TSC_G2_IO3	PA6		TSC_G6_IO3	PB13
	TSC_G2_IO4	PA7		TSC_G6_IO4	PB14
3	TSC_G3_IO1	PC5	7	TSC_G7_IO1	PE2
	TSC_G3_IO2	PB0		TSC_G7_IO2	PE3
	TSC_G3_IO3	PB1		TSC_G7_IO3	PE4
4	TSC_G4_IO1	PA9		TSC_G7_IO4	PE5
	TSC_G4_IO2	PA10	8	TSC_G8_IO1	PD12
	TSC_G4_IO3	PA11		TSC_G8_IO2	PD13
	TSC_G4_IO4	PA12		TSC_G8_IO3	PD14
				TSC_G8_IO4	PD15

Table 5. Number of capacitive sensing channels available on STM32F078CB/RB/VB devices

Analog I/O group	Number of capacitive sensing channels		
	STM32F078Vx	STM32F078Rx	STM32F078Cx
G1	3	3	3
G2	3	3	3
G3	2	2	1
G4	3	3	3

Table 5. Number of capacitive sensing channels available on STM32F078CB/RB/VB devices (continued)

Analog I/O group	Number of capacitive sensing channels		
	STM32F078Vx	STM32F078Rx	STM32F078Cx
G5	3	3	3
G6	3	3	3
G7	3	0	0
G8	3	0	0
Number of capacitive sensing channels	23	17	16

3.14 Timers and watchdogs

The STM32F078CB/RB/VB devices include up to six general-purpose timers, two basic timers and an advanced control timer.

[Table 6](#) compares the features of the different timers.

Table 6. Timer feature comparison

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/compare channels	Complementary outputs
Advanced control	TIM1	16-bit	Up, down, up/down	integer from 1 to 65536	Yes	4	3
General purpose	TIM2	32-bit	Up, down, up/down	integer from 1 to 65536	Yes	4	-
	TIM3	16-bit	Up, down, up/down	integer from 1 to 65536	Yes	4	-
	TIM14	16-bit	Up	integer from 1 to 65536	No	1	-
	TIM15	16-bit	Up	integer from 1 to 65536	Yes	2	1
	TIM16 TIM17	16-bit	Up	integer from 1 to 65536	Yes	1	1
Basic	TIM6 TIM7	16-bit	Up	integer from 1 to 65536	Yes	-	-

3.14.1 Advanced-control timer (TIM1)

The advanced-control timer (TIM1) can be seen as a three-phase PWM multiplexed on six channels. It has complementary PWM outputs with programmable inserted dead times. It

can also be seen as a complete general-purpose timer. The four independent channels can be used for:

- input capture
- output compare
- PWM generation (edge or center-aligned modes)
- one-pulse mode output

If configured as a standard 16-bit timer, it has the same features as the TIMx timer. If configured as the 16-bit PWM generator, it has full modulation capability (0-100%).

The counter can be frozen in debug mode.

Many features are shared with those of the standard timers which have the same architecture. The advanced control timer can therefore work together with the other timers via the Timer Link feature for synchronization or event chaining.

3.14.2 General-purpose timers (TIM2, 3, 14, 15, 16, 17)

There are six synchronizable general-purpose timers embedded in the STM32F078CB/RB/VB devices (see [Table 6](#) for differences). Each general-purpose timer can be used to generate PWM outputs, or as simple time base.

TIM2, TIM3

STM32F078CB/RB/VB devices feature two synchronizable 4-channel general-purpose timers. TIM2 is based on a 32-bit auto-reload up/downcounter and a 16-bit prescaler. TIM3 is based on a 16-bit auto-reload up/downcounter and a 16-bit prescaler. They feature 4 independent channels each for input capture/output compare, PWM or one-pulse mode output. This gives up to 12 input captures/output compares/PWMs on the largest packages.

The TIM2 and TIM3 general-purpose timers can work together or with the TIM1 advanced-control timer via the Timer Link feature for synchronization or event chaining.

TIM2 and TIM3 both have independent DMA request generation.

These timers are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 3 hall-effect sensors.

Their counters can be frozen in debug mode.

TIM14

This timer is based on a 16-bit auto-reload upcounter and a 16-bit prescaler.

TIM14 features one single channel for input capture/output compare, PWM or one-pulse mode output.

Its counter can be frozen in debug mode.

TIM15, TIM16 and TIM17

These timers are based on a 16-bit auto-reload upcounter and a 16-bit prescaler.

TIM15 has two independent channels, whereas TIM16 and TIM17 feature one single channel for input capture/output compare, PWM or one-pulse mode output.

The TIM15, TIM16 and TIM17 timers can work together, and TIM15 can also operate with TIM1 via the Timer Link feature for synchronization or event chaining.

TIM15 can be synchronized with TIM16 and TIM17.

TIM15, TIM16 and TIM17 have a complementary output with dead-time generation and independent DMA request generation.

Their counters can be frozen in debug mode.

3.14.3 Basic timers TIM6 and TIM7

These timers are mainly used for DAC trigger generation. They can also be used as generic 16-bit time bases.

3.14.4 Independent watchdog (IWDG)

The independent watchdog is based on an 8-bit prescaler and 12-bit downcounter with user-defined refresh window. It is clocked from an independent 40 kHz internal RC and as it operates independently from the main clock, it can operate in Stop mode. It can be used either as a watchdog to reset the device when a problem occurs, or as a free running timer for application timeout management. It is hardware or software configurable through the option bytes. The counter can be frozen in debug mode.

3.14.5 System window watchdog (WWDG)

The system window watchdog is based on a 7-bit downcounter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the APB clock (PCLK). It has an early warning interrupt capability and the counter can be frozen in debug mode.

3.14.6 SysTick timer

This timer is dedicated to real-time operating systems, but could also be used as a standard down counter. It features:

- a 24-bit down counter
- autoreload capability
- maskable system interrupt generation when the counter reaches 0
- programmable clock source (HCLK or HCLK/8)

3.15 Real-time clock (RTC) and backup registers

The RTC and the five backup registers are supplied through a switch that takes power either on V_{DD} supply when present or through the V_{BAT} pin. The backup registers are five 32-bit registers used to store 20 bytes of user application data when V_{DD} power is not present. They are not reset by a system or power reset.

The RTC is an independent BCD timer/counter. Its main features are the following:

- calendar with subseconds, seconds, minutes, hours (12 or 24 format), week day, date, month, year, in BCD (binary-coded decimal) format
- automatic correction for 28, 29 (leap year), 30, and 31 day of the month
- programmable alarm with wake up from Stop mode capability
- Periodic wakeup unit with programmable resolution and period.
- on-the-fly correction from 1 to 32767 RTC clock pulses. This can be used to synchronize the RTC with a master clock
- digital calibration circuit with 1 ppm resolution, to compensate for quartz crystal inaccuracy
- Three anti-tamper detection pins with programmable filter. The MCU can be woken up from Stop mode on tamper event detection
- timestamp feature which can be used to save the calendar content. This function can be triggered by an event on the timestamp pin, or by a tamper event. The MCU can be woken up from Stop mode on timestamp event detection
- reference clock detection: a more precise second source clock (50 or 60 Hz) can be used to enhance the calendar precision

The RTC clock sources can be:

- a 32.768 kHz external crystal
- a resonator or oscillator
- the internal low-power RC oscillator (typical frequency of 40 kHz)
- the high-speed external clock divided by 32

3.16 Inter-integrated circuit interface (I²C)

Up to two I²C interfaces (I2C1 and I2C2) can operate in multimaster or slave modes. Both can support Standard mode (up to 100 kbit/s), Fast mode (up to 400 kbit/s) and Fast Mode Plus (up to 1 Mbit/s) with extra output drive on most of the associated I/Os.

Both support 7-bit and 10-bit addressing modes, multiple 7-bit slave addresses (two addresses, one with configurable mask). They also include programmable analog and digital noise filters.

Table 7. Comparison of I²C analog and digital filters

Aspect	Analog filter	Digital filter
Pulse width of suppressed spikes	≥ 50 ns	Programmable length from 1 to 15 I2Cx peripheral clocks
Benefits	Available in Stop mode	–Extra filtering capability vs. standard requirements –Stable length
Drawbacks	Variations depending on temperature, voltage, process	Wakeup from Stop on address match is not available when digital filter is enabled.

In addition, I2C1 provides hardware support for SMBUS 2.0 and PMBUS 1.1: ARP capability, Host notify protocol, hardware CRC (PEC) generation/verification, timeouts

verifications and ALERT protocol management. I2C1 also has a clock domain independent from the CPU clock, allowing the I2C1 to wake up the MCU from Stop mode on address match.

The I2C peripherals can be served by the DMA controller.

Refer to [Table 8](#) for the differences between I2C1 and I2C2.

Table 8. STM32F078CB/RB/VB I²C implementation

I ² C features ⁽¹⁾	I2C1	I2C2
7-bit addressing mode	X	X
10-bit addressing mode	X	X
Standard mode (up to 100 kbit/s)	X	X
Fast mode (up to 400 kbit/s)	X	X
Fast Mode Plus (up to 1 Mbit/s) with extra output drive I/Os	X	X
Independent clock	X	-
SMBus	X	-
Wakeup from STOP	X	-

1. X = supported.

3.17 Universal synchronous/asynchronous receiver/transmitter (USART)

The device embeds four universal synchronous/asynchronous receivers/transmitters (USART1, USART2, USART3, USART4) which communicate at speeds of up to 6 Mbit/s.

They provide hardware management of the CTS, RTS and RS485 DE signals, multiprocessor communication mode, master synchronous communication and single-wire half-duplex communication mode. USART1 and USART2 support also SmartCard communication (ISO 7816), IrDA SIR ENDEC, LIN Master/Slave capability and auto baud rate feature, and have a clock domain independent of the CPU clock, allowing to wake up the MCU from Stop mode.

The USART interfaces can be served by the DMA controller.

Table 9. STM32F078CB/RB/VB USART implementation

USART modes/features ⁽¹⁾	USART1 and USART2	USART3 and USART4
Hardware flow control for modem	X	X
Continuous communication using DMA	X	X
Multiprocessor communication	X	X
Synchronous mode	X	X
Smartcard mode	X	-
Single-wire half-duplex communication	X	X